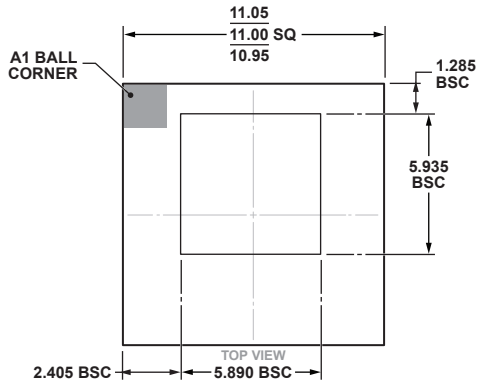
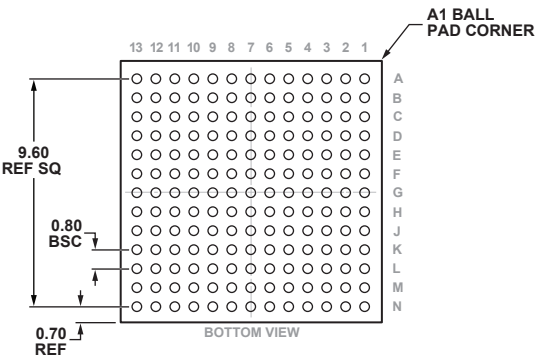
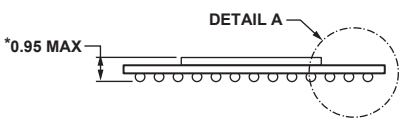
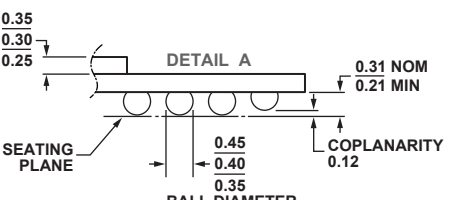
ANALOG DEVICES

169-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-169-2)
Dimensions shown in millimeters









*COMPLIANT TO JEDEC STANDARDS MO-275-FFAC-1 WITH THE EXCEPTION OF PACKAGE HEIGHT AND THICKNESS.

PKG-004675

07-10-2015-A